# Silicon P Channel Power MOS FET Power Switching

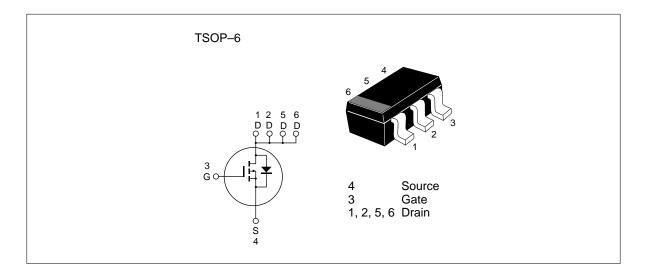
# **HITACHI**

ADE-208-754C(Z) Preliminary, 4th. Edition Dec. 1, 1998

### **Features**

- Low on-resistance
- Low drive current
- High density mounting
- 2.5V gate drive device can be driven from 3V source

#### **Outline**



### **Absolute Maximum Ratings** (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DSS</sub>	-20	V
Gate to source voltage	V <sub>GSS</sub>	±12	V
Drain current	I <sub>D</sub> *2	-4.4	A
Drain peak current	I <sub>D(pulse)</sub> *1	-17.6	A
Body-drain diode reverse drain current	*2	-4.4	A
Channel dissipation	Pch <sub>(pulse)</sub> *2	2.0	W
	Pch <sub>(continuous)</sub> *3	1.05	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW  $\leq$  10 $\mu$ s, duty cycle  $\leq$  1 %

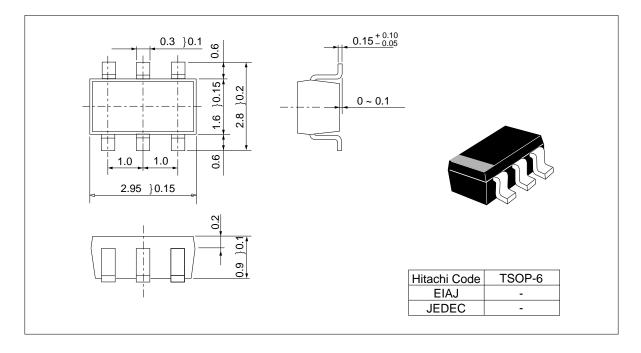
- 2. When using the alumina ceramic board (50 x 50 x 0.7 mm), PW $\leq$  5s,Ta=25°C
- 3. When using the alumina ceramic board (50 x 50 x 0.7 mm) , $Ta=25^{\circ}C$

### **Electrical Characteristics** (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-20	_	_	V	$I_D = 10 \text{mA}, V_{GS} = 0$
Gate to source leak current	I <sub>GSS</sub>		_	±0.1	μΑ	$V_{GS} = \pm 12V, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	-1	μΑ	$V_{DS} = -20 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-0.4	_	-1.4	V	$V_{DS} = -10V$ , $I_D = -1mA$
Static drain to source on state	$R_{\scriptscriptstyle DS(on)}$	_	55	65	mΩ	$I_D = -3A$ , $V_{GS} = -4.5V^{*1}$
resistance	$R_{\scriptscriptstyle DS(on)}$	_	85	110	mΩ	$I_D = -3A, V_{GS} = -2.5V^{*1}$
Forward transfer admittance	y <sub>fs</sub>	4	7	_	S	$I_D = -3A$ , $V_{DS} = -10V^{*1}$
Input capacitance	Ciss	_	700	_	pF	$V_{DS} = -10V$
Output capacitance	Coss	_	180	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	120	_	pF	f = 1MHz
Turn-on delay time	$t_{\text{d(on)}}$	_	15	_	ns	$V_{GS} = -4.5V, I_{D} = -3A$
Rise time	t <sub>r</sub>	_	100	_	ns	$R_L = 3.3\Omega$
Turn-off delay time	t <sub>d(off)</sub>	_	70	_	ns	
Fall time	t <sub>f</sub>	_	70	_	ns	
Body-drain diode forward voltage	$V_{DF}$	_	-0.95	_	V	$IF = -4.4A, V_{GS} = 0 *1$
Body-drain diode reverse recovery time	t <sub>rr</sub>	_	50	_	ns	$IF = -4.4A, V_{GS} = 0$ diF/ dt =-20A/ $\mu$ s
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Note: 1. Pulse test

### **Package Dimensions (Unit: mm)**



#### **Cautions**

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